Layer	Name	Material	Thickness	Constant	Board Layer Stack
1	Top Overlay				
2	Top Solder	Solder Resist	0.79mil	3.5	
3	Top Layer	Copper	0.67mil		
4	Dielectric1	FR-4	12.21mil	4.2	
5	MidLayer 1	Copper	1.38mil		
6	Dielectric 2	FR-4	31.50mil	4.8	
7	MidLayer 2	Copper	1.38mil		
8	Dielectric 3	FR-4	12.21mil	4.2	
9	Bottom Layer	Copper	0.67mil		
10	Bottom Solder	Solder Resist	0.79mil	3.5	
11	Bottom Overlay				

DESIGN INFORMATION

MIN. TRACK WIDTH: 7 MIL
MIN. CLEARANCE: 5.9 MIL
MIN. VIA PAD SIZE: 36 MIL
MINIMUM ANNULAR RING 0.05mm (2MIL) EXTERNAL
PER IPC-D-275 CLASS 2 LEVEL C
REGISTRATION TOLERANCES: METAL +/- 5 MIL, HOLES +/- 3 MIL
HOLE SIZE TOLERANCE (UNLESS OTHERWISE SPECIFIED): +/- 3 MIL

MATERIAL:
[ ] FR-408 [X] FR-4 High Tg [ ] OTHER _____
THICKNESS: [X] 62 MIL (1.6mm) +/-10% [ ] OTHER _____
TOLERANCE: [X] ANSI IPC-6012 TYPE 3 CLASS 2
[ ] OTHER +/- _____
BOW & TWIST: [X] ANSI IPC-6012 TYPE 3 CLASS 2
[ ] OTHER +/- _____

DRILLING:
REFERENCE: [X] AS SHOWN [X] NC_DRILL FILES
PTH COPPER THICKNESS: [X] 20-30 um [ ] OTHER _____

BOARD FINISH:
SILKSCREEN: [X] TOP [X] BOTTOM
SILKSCREEN COLOR: [X] WHITE [ ] OTHER _____
SOLDER RESIST COLOR: [X] GREEN [ ] OTHER _____
[X] MATTE [ ] SEMI-GLOSS

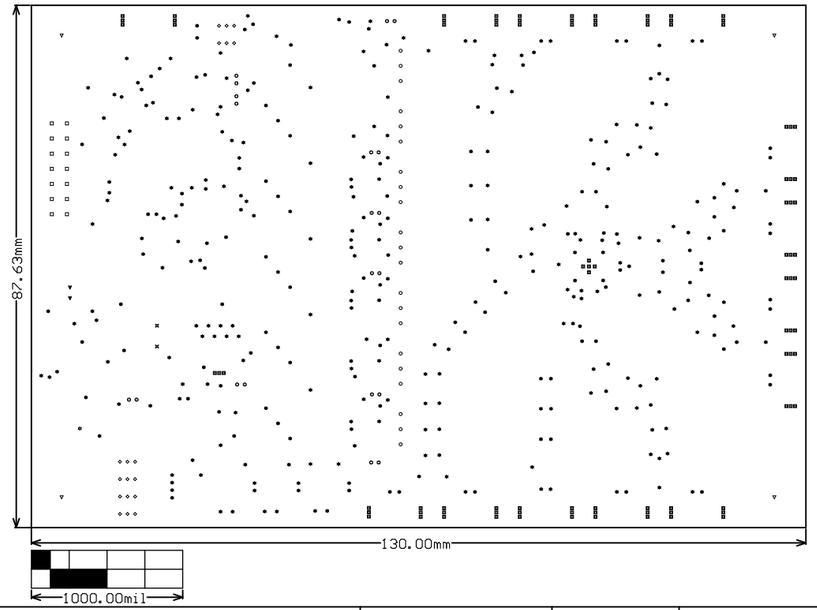
SURFACE FINISH: [X] IMMERSION GOLD (ENIG) [ ] ENEPIG
[ ] IMM. TIN/SILVER OR EQUIV [ ] OTHER _____

ARRAY/PANEL: [ ] CUT AND TRIM PER M1 BOARD OUTLINE
[ ] N.C. ROUTE [X] V. SCORE

CERTIFICATION: MATERIALS AND WORKMANSHIP FOR ALL PCBS TO MEET OR EXCEED THE REQUIREMENTS OF:
[X] ANSI IPC-A-600F CLASS -> [ ] 1 [X] 2 [ ] 3
[X] RoHS [ ] OTHER PER ORDER

ALL BOARDS MUST MEET OR EXCEED UL94-V0 REQUIREMENTS.
PCB MUST BEAR THE UL94V-0 UL REGISTERED MATERIAL ID NUMBER

ADDITIONAL REQUIREMENTS:
MICROSECTION: [ ] YES
BARE BOARD ELEC. TEST: [ ] NONE [X] REQUIRED [ ] PER ORDER



Symbol	Quantity	Finished Hole Size	Plated	Hole Type	Drill Layer Pair	Hole Tolerance
▽	2	31.50mil (0.800mm)	NPTH	Round	Top Layer - Bottom Layer	
◘	92	7.87mil (0.200mm)	PTH	Round	Top Layer - Bottom Layer	
✽	365	16.00mil (0.406mm)	PTH	Round	Top Layer - Bottom Layer	
◇	18	27.56mil (0.700mm)	PTH	Round	Top Layer - Bottom Layer	
✪	20	28.00mil (0.711mm)	PTH	Round	Top Layer - Bottom Layer	
□	14	37.00mil (0.940mm)	PTH	Round	Top Layer - Bottom Layer	
✲	1	40.00mil (1.016mm)	PTH	Round	Top Layer - Bottom Layer	
○	21	45.28mil (1.150mm)	PTH	Round	Top Layer - Bottom Layer	
⌘	2	47.24mil (1.200mm)	PTH	Round	Top Layer - Bottom Layer	+7.87mil/-0.00mil
▽	4	125.98mil (3.200mm)	PTH	Round	Top Layer - Bottom Layer	
	539 Total					

TEXAS INSTRUMENTS

PROJECT TITLE: CDCI6214EVM
DESIGNED FOR: Public Release
FILE NAME: SV601290A_PCB.PcbDoc

ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: SV601290	REV: A	SVN REV: Not In VersionControl
LAYER NAME = [illegible]ions	TID #: N/A		
PLOT NAME = Fabrication Drawing	GENERATED : 10/26/2017 10:42:03 AM	TEXAS INSTRUMENTS	

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ENGINEER:	LAYOUT BY:
Kammermayer, Patrick	Kammermayer, Patrick
SCALE: 1.00	ALTIUM DESIGNER VERSION: 17.1.5.472